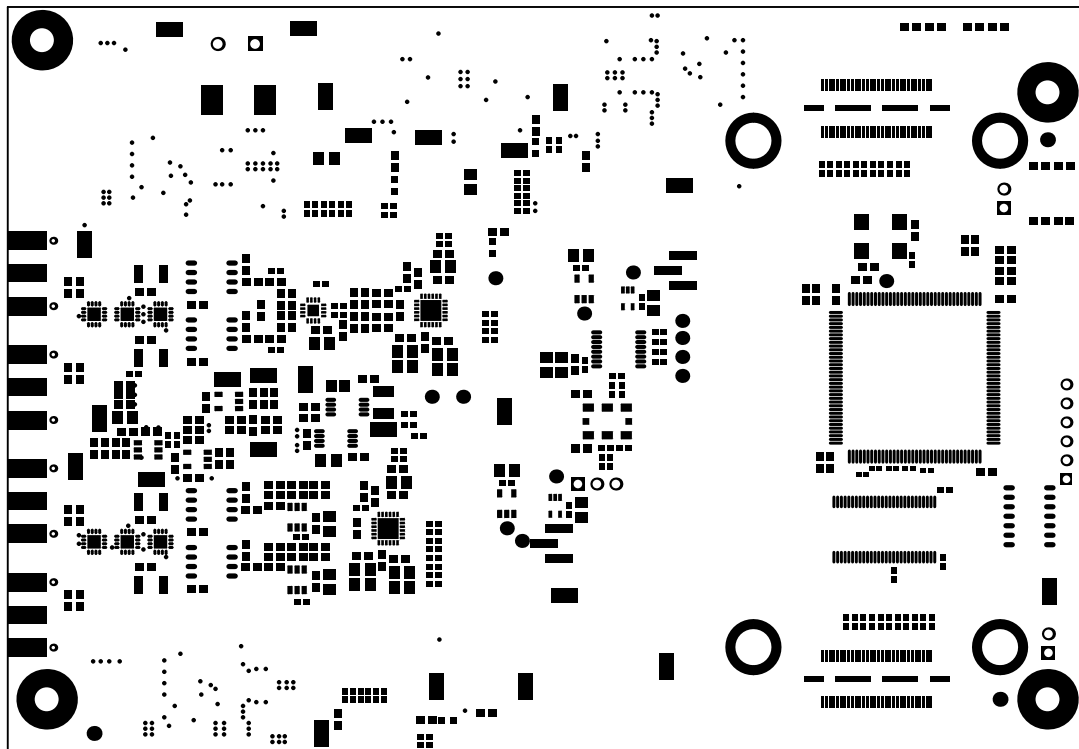
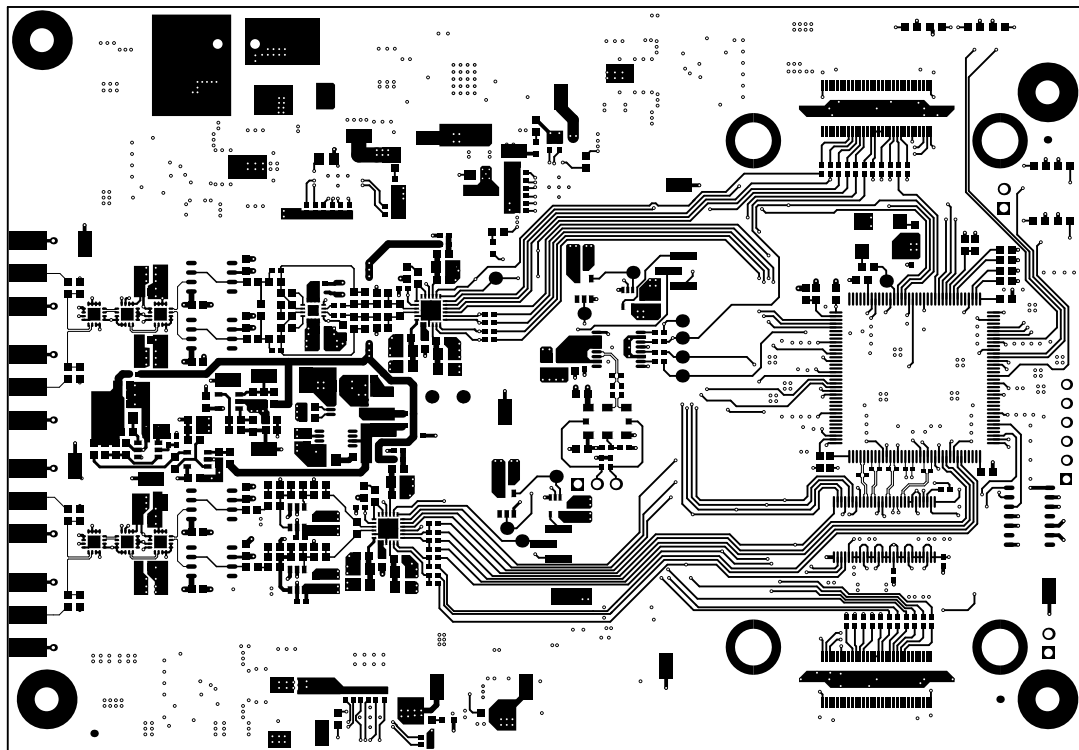


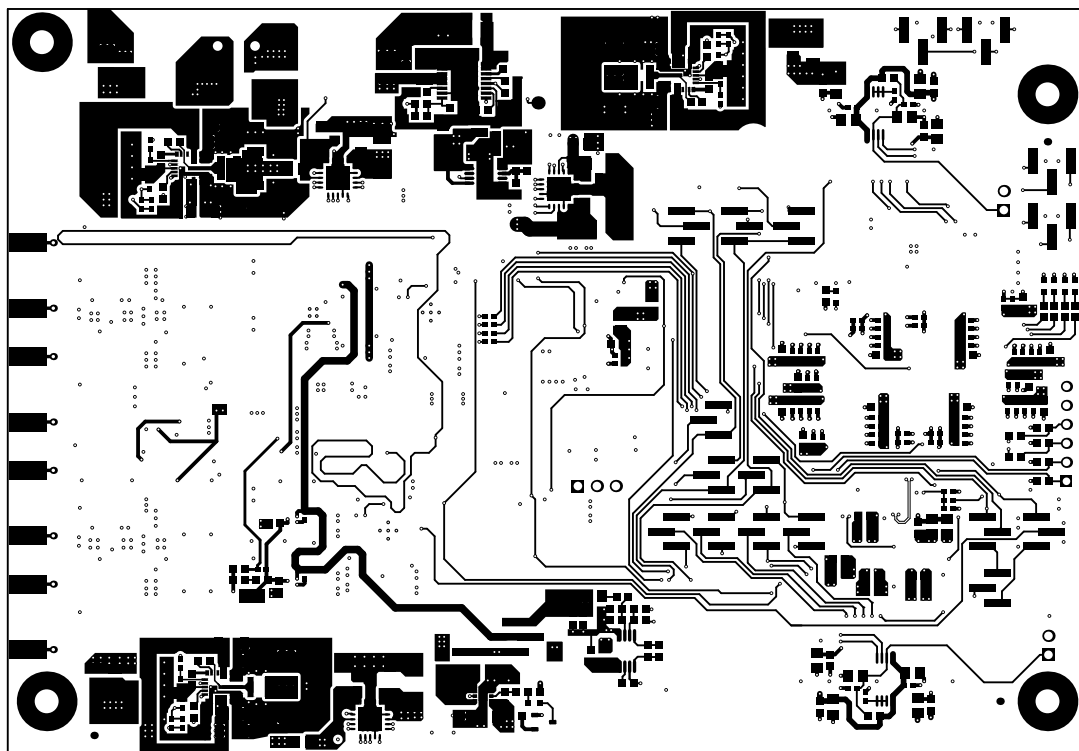
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01051	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: 01051		
PLOT NAME = Top Overlay	GENERATED : 4/7/2017	12:42:00 PM	TEXAS INSTRUMENTS



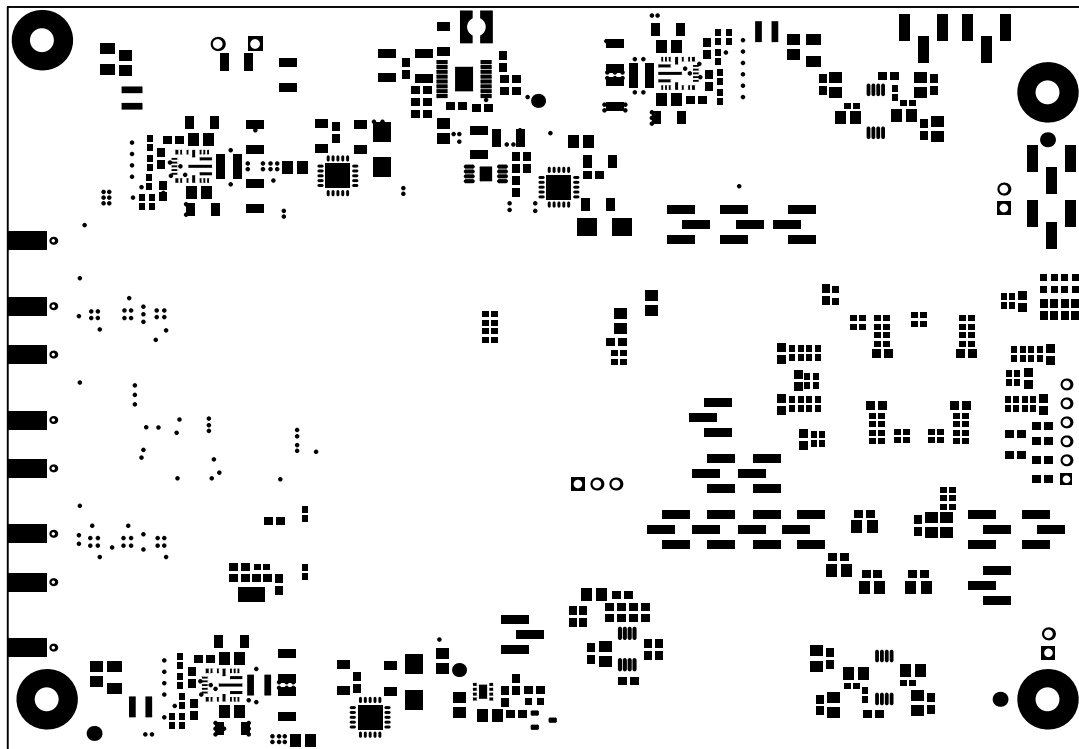
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01051	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: 01051		
PLOT NAME = Top Solder Mask	GENERATED : 4/7/2017 12:42:01 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01051	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Layer 1 - Top Layer	TID #: 01051		
PLOT NAME = Top Layer	GENERATED : 4/7/2017 12:42:02 PM	TEXAS INSTRUMENTS	



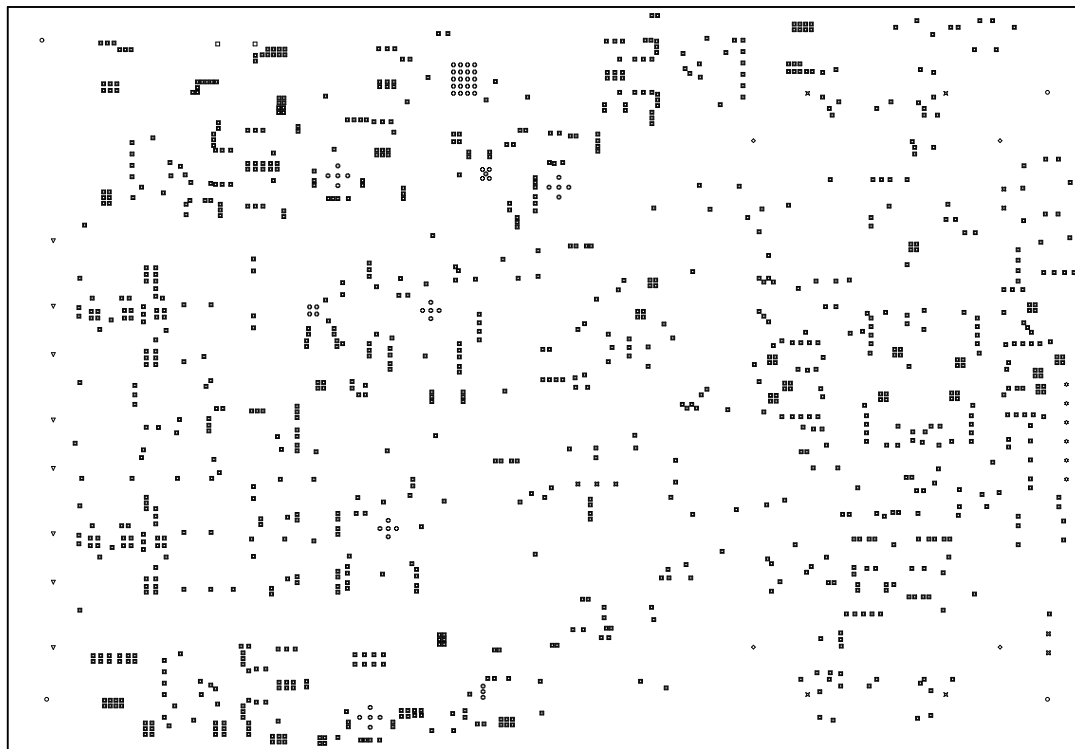
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01051	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Layer 4 - Bottom Layer	TID #: 01051		
PLOT NAME = Bottom Layer	GENERATED : 4/7/2017 12:42:03 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01051	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: 01051		
PLOT NAME = Bottom Solder Mask	GENERATED : 4/7/2017 12:42:04 PM	TEXAS INSTRUMENTS	

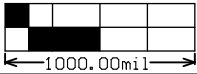


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01051	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: 01051		
PLOT NAME = Bottom Overlay	GENERATED : 4/7/2017	12:42:05 PM	TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⊠	4	40.00mil (1.016mm)	NPTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
◇	4	173.23mil (4.400mm)	NPTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
⊕	57	7.87mil (0.200mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
■	1044	10.00mil (0.254mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
▽	8	18.00mil (0.457mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
⊛	6	40.00mil (1.016mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
⊗	7	45.28mil (1.150mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
□	2	51.18mil (1.300mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
○	4	125.98mil (3.200mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
	1136 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01051	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: 01051		
PLOT NAME = Drill Drawing	GENERATED : 4/7/2017 12:42:06 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01051	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: 01051		
PLOT NAME = Board Dimensions	GENERATED : 4/7/2017	12:42:07 PM	TEXAS INSTRUMENTS



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